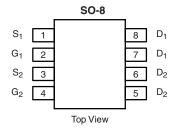




N- and P-Channel 40-V (D-S) MOSFET

PRODUCT SUMMARY							
	V _{DS} (V)	$R_{DS(on)}(\Omega)$	I _D (A) ^a	Q _g (Typ.)			
N-Channel	40	0.027 at V _{GS} = 10 V	6.0	9.6			
		0.032 at $V_{GS} = 4.5 \text{ V}$	4.8	9.0			
P-Channel	- 40	$0.029 \text{ at V}_{GS} = -10 \text{ V}$	- 6.0	21			
		0.039 at $V_{GS} = -4.5 \text{ V}$	- 4.9	۷۱			



Ordering Information: Si4569DY-T1-E3 (Lead (Pb)-free)

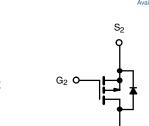
Si4569DY-T1-GE3 (Lead (Pb)-free and Halogen-free)

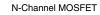
FEATURES

- Halogen-free According to IEC 61249-2-21 Available
- TrenchFET[®] Power MOSFET
- 100 % R_g and UIS Tested

APPLICATIONS

· CCFL Inverter





P-Channel MOSFET

HALOGEN

FREE

Parameter	Symbol	N-Channel	P-Channel	Unit	
Drain-Source Voltage	V _{DS}	40	- 40	V	
Gate-Source Voltage	V_{GS}	±	V		
Continuous Duois Courset /T 150 °C)	T _C = 25 °C		7.6	- 7.9	
	T _C = 70 °C		6.0	- 6.3	
Continuous Drain Current (T _J = 150 °C)	T _A = 25 °C	I _D	6.0 ^{b, c}	- 6.1 ^{b, c}	
	T _A = 70 °C	1	4.8 ^{b, c}	- 4.9 ^{b, c}	
Pulsed Drain Current (10 µs Pulse Width)	I _{DM}	20	- 20	Α	
Source-Drain Current Diode Current	T _C = 25 °C	I_	2.6	- 2.6	
Source-Drain Current blode Current	T _A = 25 °C	I _S	1.6 ^{b, c}	- 1.6 ^{b, c}	
Pulsed Source-Drain Current	I _{SM}	20	- 20		
Single Pulse Avalanche Current	L = 0.1 mH	I _{AS}	10	20	
Single Pulse Avalanche Energy	L = 0.1 IIII	E _{AS}	5	20	mJ
	T _C = 25 °C		3.1	3.2	
Maximum Power Dissipation	T _C = 70 °C	P _D	2	2.1	W
	T _A = 25 °C	FD	2 ^{b, c}	2 ^{b, c}	VV
	T _A = 70 °C		1.28 ^{b, c}	1.28 ^{b, c}	
Operating Junction and Storage Temperature R	T _J , T _{stg}	- 55 t	- 55 to 150		

THERMAL RESISTANCE RATINGS									
			N-Channel P-Channel						
Parameter		Symbol	Тур.	Max.	Тур.	Max.	Unit		
Maximum Junction-to-Ambient ^{b, d}	t ≤ 10 s	R _{thJA}	49	62.5	47	62.5	°C/W		
Maximum Junction-to-Foot (Drain)	Steady State	R _{thJF}	30	40	29	38	C/VV		

Notes

- a. Based on $T_C = 25$ °C.
- b. Surface Mounted on 1" x 1" FR4 board.
- c. t = 10 s
- d. Maximum under Steady State conditions is 120 °C/W (N-Channel) and 110 °C/W (P-Channel).

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Parameter	Symbol	Test Conditions		Min.	Typ. ^a	Max.	Unit
Static							
D : 0		$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	N-Ch	40			
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V, } I_{D} = -250 \mu\text{A}$	P-Ch	- 40			-
	A) (/T	I _D = 250 μA	N-Ch		37		- - - V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	I _D = - 250 μA	P-Ch		- 38		
V Tompovotive Coefficient	A) / /T	I _D = 250 μA	N-Ch		- 5		
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I _D = - 250 μA	P-Ch		4.0		
Oaks Thousehold Walks as		$V_{DS} = V_{GS}, I_D = 250 \mu A$	N-Ch	0.6		2.0	
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	P-Ch	- 0.8		- 2.2	
Gate-Body Leakage	1	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 16 \text{ V}$	N-Ch			100	nA
	I _{GSS}		P-Ch			- 100	
		$V_{DS} = 40 \text{ V}, V_{GS} = 0 \text{ V}$	N-Ch			1	
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = -40 \text{ V}, V_{GS} = 0 \text{ V}$	P-Ch			- 1	- μΑ
Zero Gate Voltage Drain Guirent	USS	$V_{DS} = 40 \text{ V}, V_{GS} = 0 \text{ V}, T_J = 55 ^{\circ}\text{C}$	N-Ch			10	
		$V_{DS} = -40 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 ^{\circ}\text{C}$	P-Ch			- 10	
On-State Drain Current ^b		$V_{DS} = 5 \text{ V}, V_{GS} = 10 \text{ V}$	N-Ch	20			Α
	I _{D(on)}	$V_{DS} = -5 \text{ V}, V_{GS} = -10 \text{ V}$	P-Ch	- 20			
	R _{DS(on)}	$V_{GS} = 10 \text{ V}, I_D = 6 \text{ A}$	N-Ch		0.022	0.027	
		$V_{GS} = -10 \text{ V}, I_D = -6 \text{ A}$	P-Ch		0.024	0.029	Ω
Drain-Source On-State Resistance ^b		$V_{GS} = 4.5 \text{ V}, I_D = 4.8 \text{ A}$	N-Ch		0.026	0.032	
		$V_{GS} = -4.5 \text{ V}, I_D = -4.9 \text{ A}$	P-Ch		0.031	0.039	
		$V_{DS} = 15 \text{ V}, I_{D} = 6 \text{ A}$	N-Ch		20		S
Forward Transconductance ^b	9 _{fs}	$V_{DS} = -15 \text{ V}, I_{D} = -6 \text{ A}$	P-Ch		17		
Dynamic ^a			•	<u> </u>		<u>I</u>	
Input Congoitones	C _{iss}		N-Ch		855		
Input Capacitance	Oiss	N-Channel	P-Ch		1505		
Output Capacitance	C _{oss}	$V_{DS} = 20 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	N-Ch		105		рF
Carpat Capacitaco	- 035	P-Channel	P-Ch		230		
Reverse Transfer Capacitance	C _{rss}	$V_{DS} = -20 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	N-Ch		65		
·		V 00 V V 40 V L 5 A	P-Ch		175		
	$Q_{ m g}$	$V_{DS} = 20 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 5 \text{ A}$	N-Ch		21	32	nC
Total Gate Charge		$V_{DS} = -20 \text{ V}, V_{GS} = -10 \text{ V}, I_{D} = -5 \text{ A}$	P-Ch		41	62	
		N-Channel V_{DS} = 20 V, V_{GS} = 4.5 V, I_{D} = 5 A	N-Ch		9.6	14.5	
			P-Ch		21	31	
Gate-Source Charge			N-Ch		2.3		
	Q _{gd}	P-Channel $V_{DS} = -20 \text{ V}, V_{GS} = -4.5 \text{ V}, I_{D} = -5 \text{ A}$	P-Ch N-Ch		4.5 3.2		
Gate-Drain Charge			P-Ch		9.2		1
	R _g	f = 1 MHz	N-Ch		2.5	3.8	
Gate Resistance			P-Ch	-	6.5	10	Ω



Si4569DY Vishay Siliconix

Parameter	Symbol	Test Conditions			Typ. ^a	Max.	Unit
Dynamic ^a					l l		
Turn-On Delay Time	t _{d(on)}	N-Channel	N-Ch		6	12	
<u> </u>	u(on)	$V_{DD} = 20 \text{ V}, R_L = 4 \Omega$	P-Ch N-Ch		7	14	
Rise Time	t _r	In ~ 5 A Varu = 10 V R = 1 O			11 15	20 25	
	t _{d(off)}	D. Ohamasi	P-Ch N-Ch		24	36	
Turn-Off Delay Time		P-Channel $V_{DD} = -20 \text{ V, } R_{I} = 4 \Omega$	P-Ch		51	77	
Eall Times		$I_{D} \cong -5 \text{ A}, V_{GEN} = -10 \text{ V}, R_{a} = 1 \Omega$	N-Ch		6	12	
Fall Time	t _f	ID = - 3 A, VGEN = - 10 V, Fig = 132			54	81	ns
Turn-On Delay Time	t., ,				12	20	
Turn-On Delay Time	t _{d(on)}	N-Channel $V_{DD} = 20 \text{ V, R}_{L} = 4 \Omega$	P-Ch		26	40	
Rise Time	t _r	$I_D \cong 5 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_q = 1 \Omega$	N-Ch		60	90	
	7	1D = 571, VGEN = 4.5 V, 11g = 1 32	P-Ch		105	160	
		P-Channel	N-Ch		22	33	
	u(on)	V_{DD} = - 20 V, R_L = 4 Ω $I_D \cong$ - 5 A, V_{GEN} = - 4.5 V, R_g = 1 Ω	P-Ch		60	90	- -
Fall Time	t _f		N-Ch P-Ch		5 60	10 90	
Drain-Source Body Diode Characteristic	es		F-CII		60	90	
-			N-Ch			2.6	
Continuous Source-Drain Diode Current I _S T _C		T _C = 25 °C	P-Ch			- 2.6	
	I _{SM}		N-Ch			20	Α
Pulse Diode Forward Current ^a			P-Ch			- 20	
Dadu Diada Vallana	V _{SD}	I _S = 1.5 A	N-Ch		0.73	1.2	V
Body Diode Voltage		I _S = - 1.6 A	P-Ch		- 0.73	- 1.2	V
Body Diode Reverse Recovery Time	+		N-Ch		26	40	nc
Body blode neverse necovery fillie	t _{rr}	N. O.	P-Ch		30	45	ns
Body Diode Reverse Recovery Charge	Q _{rr}	N-Channel $I_F = 5 \text{ A}$, dl/dt = 100 A/ μ s, $T_J = 25 ^{\circ}\text{C}$	N-Ch		21	32	nC
	11	1 - 37, απαί - 1007 γμο, 1 - 25 - 5	P-Ch		24	36	
Reverse Recovery Fall Time	t _a	P-Channel	N-Ch		13		
-		$I_F = -5 \text{ A}, \text{ dI/dt} = -100 \text{ A/}\mu\text{s}, T_J = 25 ^{\circ}\text{C}$	P-Ch		15		ns
Reverse Recovery Rise Time	t _b		N-Ch P-Ch		13 15		

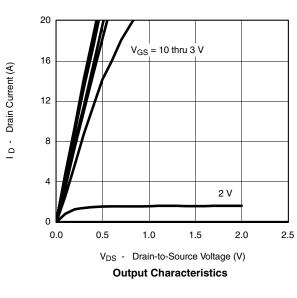
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

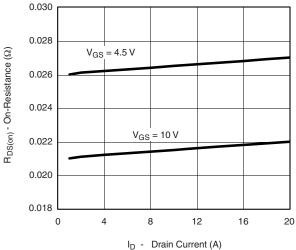
a. Guaranteed by design, not subject to production testing.

b. Pulse test; pulse width \leq 300 μ s, duty cycle \leq 2 %.

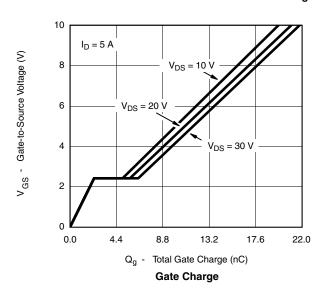


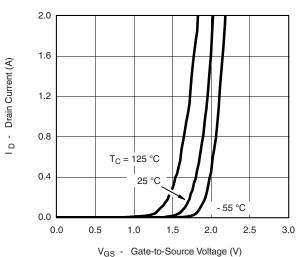
N-CHANNEL TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



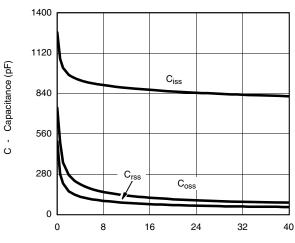


On-Resistance vs. Drain Current and Gate Voltage

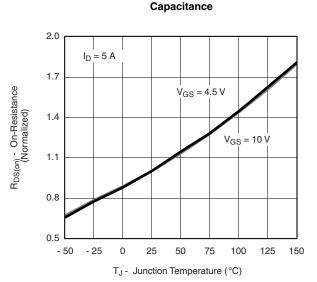




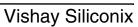
Transfer Characteristics



V_{DS} - Drain-to-Source Voltage (V)

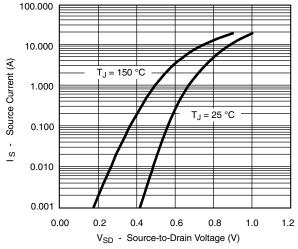


On-Resistance vs. Junction Temperature

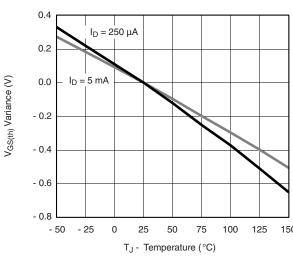




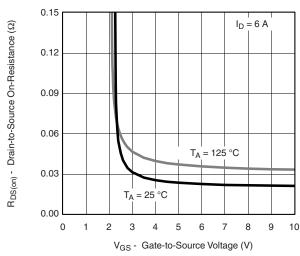
N-CHANNEL TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



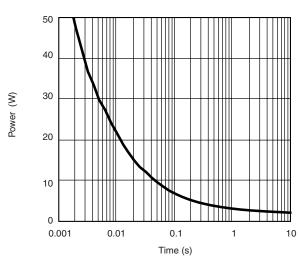
Source-Drain Diode Forward Voltage



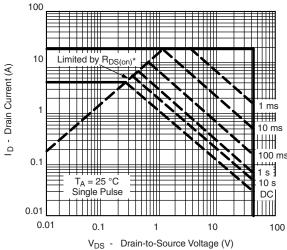
Threshold Voltage



On-Resistance vs. Gate-to-Source Voltage



Single Pulse Power, Junction-to-Ambient

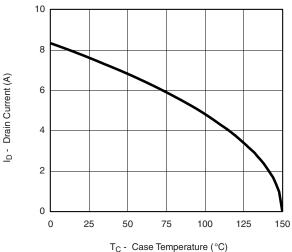


 v_{DS} - Drain-to-Source voltage (V) * V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified

Safe Operating Area, Junction-to-Ambient

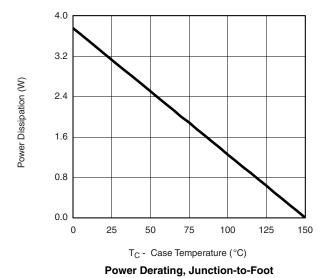
VISHAY

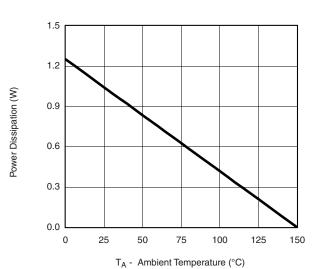
N-CHANNEL TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



1_C - Case remperature (°C

Current Derating*



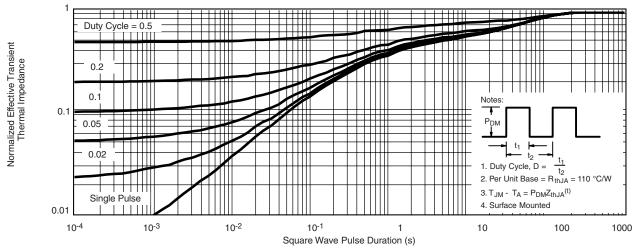


Power Derating, Junction-to-Ambient

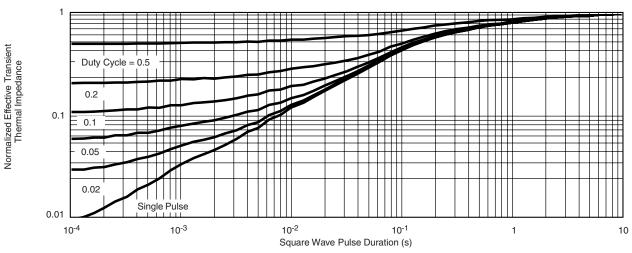
^{*} The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.



N-CHANNEL TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



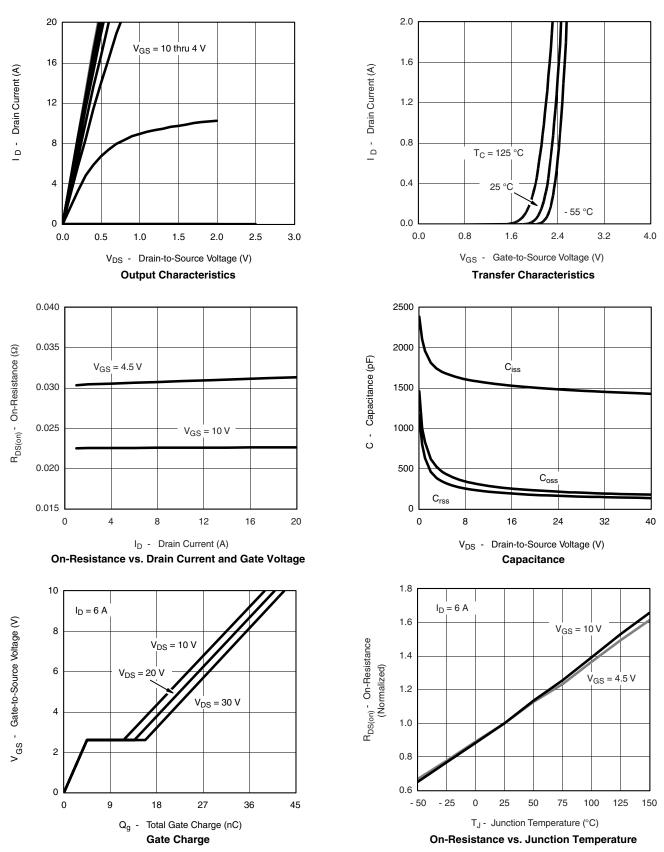
Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Case

VISHAY

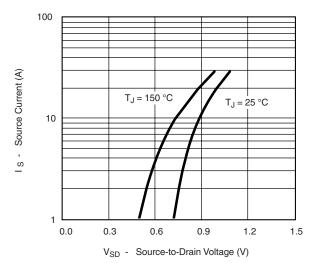
P-CHANNEL TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



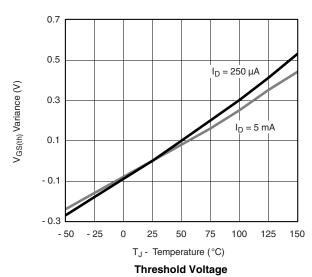




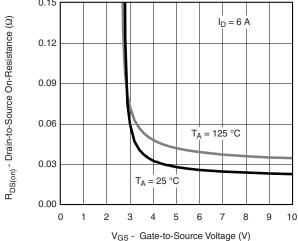
P-CHANNEL TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



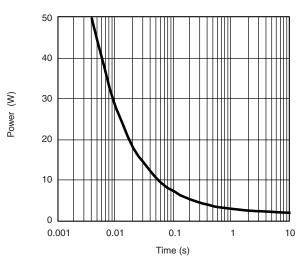
Source-Drain Diode Forward Voltage



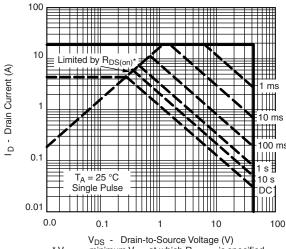
0.15



On-Resistance vs. Gate-to-Source Voltage



Single Pulse Power, Junction-to-Ambient

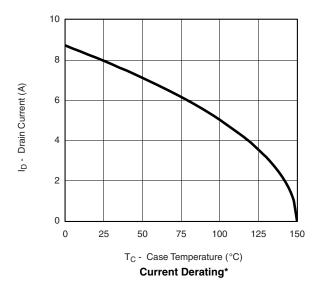


* V_{GS} > minimum V_{GS} at which R_{DS(on)} is specified

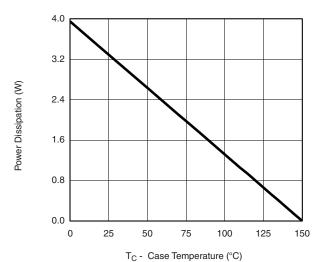
Safe Operating Area, Junction-to-Ambient

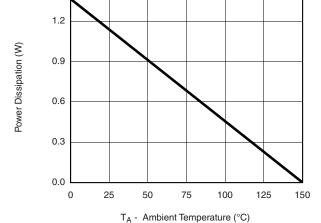
VISHAY.

P-CHANNEL TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



1.5





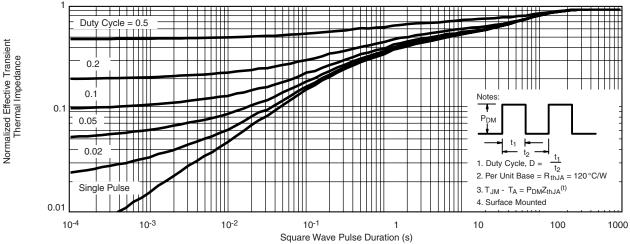
Power Derating, Junction-to-Foot

Power Derating, Junction-to-Ambient

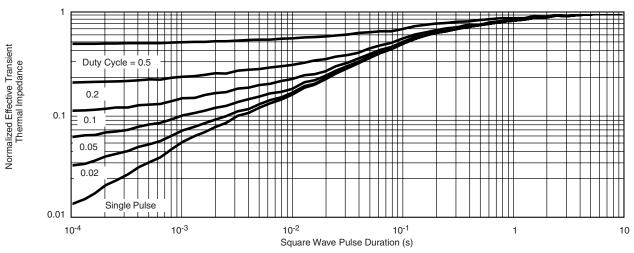
^{*} The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.



P-CHANNEL TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Case

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